

March 2015

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FDMS86150

N-Channel Shielded Gate PowerTrench[®] MOSFET 100 V, 80 A, 4.85 m Ω

Features

- Shielded Gate MOSFET Technology
- Max $r_{DS(on)}$ = 4.85 m Ω at V_{GS} = 10 V, I_D = 16 A
- Max $r_{DS(on)} = 7.8 \text{ m}\Omega$ at $V_{GS} = 6 \text{ V}$, $I_D = 13 \text{ A}$
- \blacksquare Advanced Package and Silicon combination for low $r_{\text{DS}(\text{on})}$ and high efficiency
- MSL1 robust package design
- 100% UIL tested
- RoHS Compliant

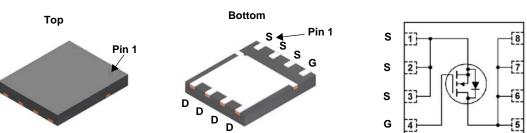


General Description

This N-Channel MOSFET is produced using Fairchild Semiconductor's advanced PowerTrench® process that incorporates Shielded Gate technology. This process has been optimized for the on-state resistance and yet maintain superior switching performance.

Applications

- Primary DC-DC MOSFET
- Secondary Synchronous Rectifier
- Load Switch



Power 56

MOSFET Maximum Ratings T_A = 25 °C unless otherwise noted

Symbol	Paramet		Ratings	Units	
V _{DS}	Drain to Source Voltage			100	V
V_{GS}	Gate to Source Voltage			±20	V
I _D	Drain Current -Continuous	T _C = 25 °C		80	
	-Continuous $T_A = 25 ^{\circ}\text{C}$ (Note 1a)		(Note 1a)	16	Α
	-Pulsed			300	
E _{AS}	Single Pulse Avalanche Energy		(Note 3)	726	mJ
В	Power Dissipation	T _C = 25 °C		156	W
P_{D}	Power Dissipation	T _A = 25 °C	(Note 1a)	2.7	VV
T _J , T _{STG}	Operating and Storage Junction Temperatu	ıre Range		-55 to +150	°C

Thermal Characteristics

$R_{\theta JC}$	Thermal Resistance, Junction to Case	0.8	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (Note 1a)	45	C/VV

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDMS86150	FDMS86150	Power 56	13 "	12 mm	3000 units

Electrical Characteristics $T_J = 25$ °C unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units	
Off Characteristics							
BV_{DSS}	Drain to Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	100			V	
$\frac{\Delta BV_{DSS}}{\Delta T_{J}}$	Breakdown Voltage Temperature Coefficient	I_D = 250 μ A, referenced to 25 °C		72		mV/°C	
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 80 V, V _{GS} = 0 V			1	μΑ	
I _{GSS}	Gate to Source Leakage Current	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$			±100	nA	

On Characteristics

V _{GS(th)}	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 250 \mu A$	2	3	4	V	
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	$I_D = 250 \mu A$, referenced to 25 °C		-10		mV/°C	
		V _{GS} = 10 V, I _D = 16 A		3.9	4.85		
r _{DS(on)}	Static Drain to Source On Resistance	$V_{GS} = 6 \text{ V}, I_D = 13 \text{ A}$		6	7.8	mΩ	
		$V_{GS} = 10 \text{ V}, I_D = 16 \text{ A}, T_J = 125 ^{\circ}\text{C}$		7.3	9.1		
9 _{FS}	Forward Transconductance	V _{DS} = 10 V, I _D = 16 A		53		S	

Dynamic Characteristics

C _{iss}	Input Capacitance	V 50.V.V 0.V		3055	4065	pF
C _{oss}	Output Capacitance	$V_{DS} = 50 \text{ V}, V_{GS} = 0 \text{ V},$ f = 1 MHz		696	930	pF
C _{rss}	Reverse Transfer Capacitance	1 - 1 WII 12		29	50	pF
R_g	Gate Resistance		0.1	0.7	3.6	Ω

Switching Characteristics

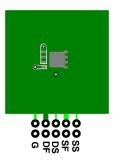
t _{d(on)}	Turn-On Delay Time			18	33	ns
t _r	Rise Time	$V_{DD} = 50 \text{ V}, I_D = 16 \text{ A},$		8.3	17	ns
t _{d(off)}	Turn-Off Delay Time	$V_{GS} = 10 \text{ V}, R_{GEN} = 6 \Omega$		28	45	ns
t _f	Fall Time			6	12	ns
Qg	Total Gate Charge	V _{GS} = 0 V to 10 V		44	62	nC
Qg	Total Gate Charge	$V_{GS} = 0 \text{ V to 5 V}$ $V_{DD} = 50 \text{ V}$,	25	35	nC
Q _{gs}	Gate to Source Charge	I _D = 16 A		12.9		nC
Q_{gd}	Gate to Drain "Miller" Charge			9.2		nC

Drain-Source Diode Characteristics

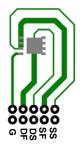
V _{SD} Source to Drain Diode Forward Voltage	Source to Drain Diode, Forward Voltage	$V_{GS} = 0 \text{ V}, I_{S} = 2.1 \text{ A}$ (Note 2)		0.69	1.2	\ <u>'</u>	
	$V_{GS} = 0 \text{ V}, I_S = 16 \text{ A}$ (Note 2)		0.78	1.3	V		
t _{rr}	Reverse Recovery Time	- I _F = 16 A, di/dt = 100 A/μs		69	110	ns	
Q _{rr}	Reverse Recovery Charge			94	150	nC	

Notes:

¹ R_{0JA} is determined with the device mounted on a 1 in² pad 2 oz copper pad on a 1.5 x 1.5 in. board of FR-4 material. R_{0JC} is guaranteed by design while R_{0CA} is determined by the user's board design.



a. 45 °C/W when mounted on a 1 in² pad of 2 oz copper.



 b. 115 °C/W when mounted on a minimum pad of 2 oz copper.

- 2. Pulse Test: Pulse Width < 300 $\mu\text{s},$ Duty cycle < 2.0%.
- 3. E_{AS} of 726 mJ is based on starting T_J = 25 °C, L = 3 mH, I_{AS} = 22 A, V_{DD} = 100 V, V_{GS} = 10 V, 100% test at L = 0.1 mH, I_{AS} = 69 A.

Typical Characteristics T_J = 25 °C unless otherwise noted

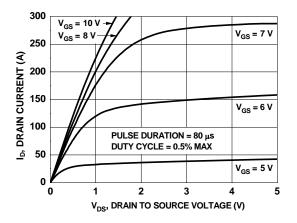


Figure 1. On Region Characteristics

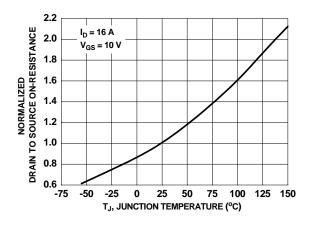


Figure 3. Normalized On Resistance vs Junction Temperature

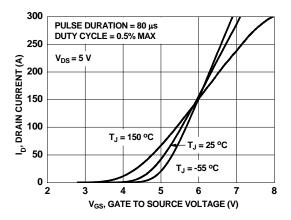


Figure 5. Transfer Characteristics

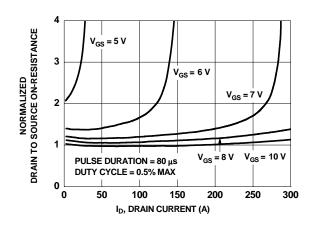


Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

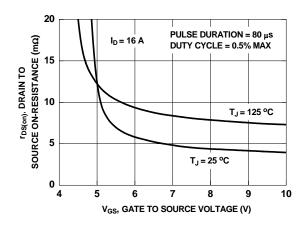


Figure 4. On-Resistance vs Gate to Source Voltage

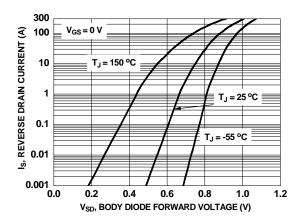


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

Typical Characteristics $T_J = 25$ °C unless otherwise noted

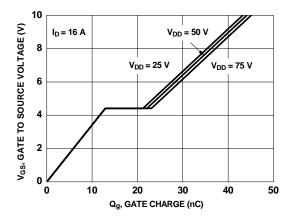


Figure 7. Gate Charge Characteristics

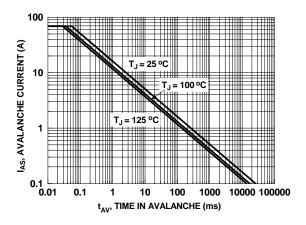


Figure 9. Unclamped Inductive Switching Capability

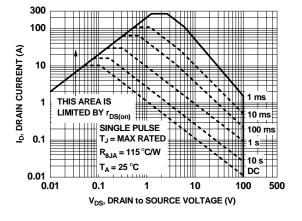


Figure 11. Forward Bias Safe Operating Area

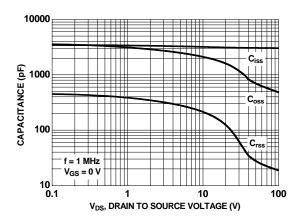


Figure 8. Capacitance vs Drain to Source Voltage

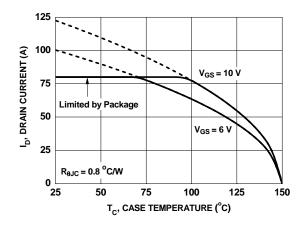


Figure 10. Maximum Continuous Drain Current vs Case Temperature

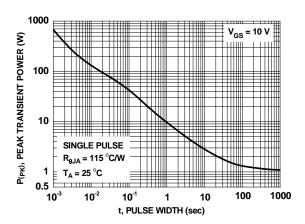


Figure 12. Single Pulse Maximum Power Dissipation

Typical Characteristics T_J = 25 °C unless otherwise noted

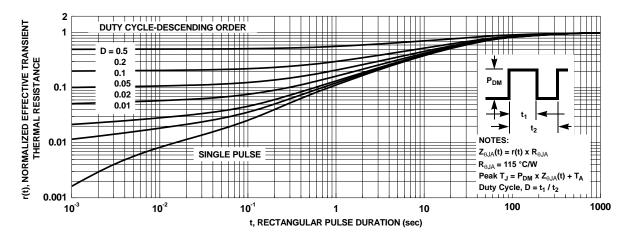
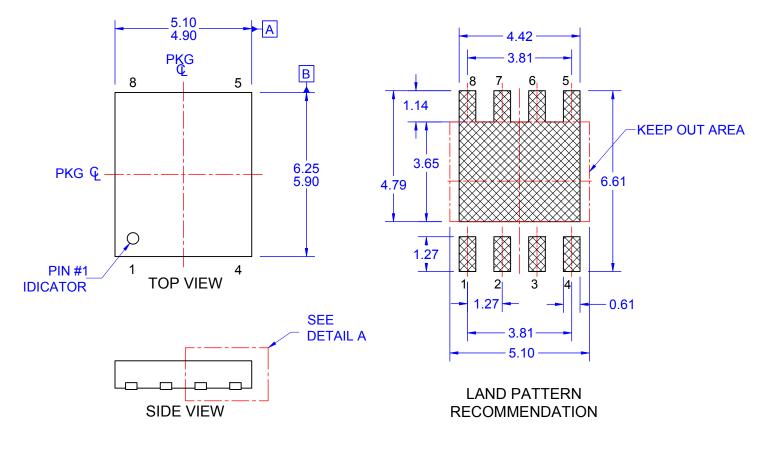
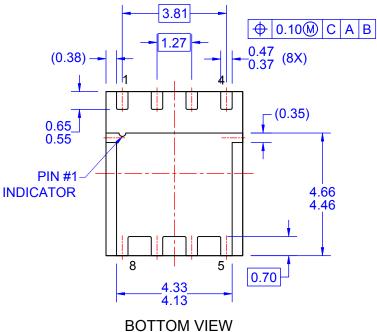
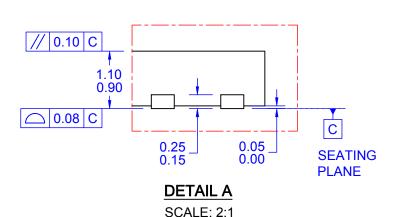


Figure 13. Junction-to-Ambient Transient Thermal Response Curve







NOTES: UNLESS OTHERWISE SPECIFIED

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- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS DO NOT INCLUDE BURRS OR MOLD FLASH. MOLD FLASH OR BURRS DOES NOT EXCEED 0.10MM.
- D) DIMENSIONING AND TOLERANCING PER ASME Y14.5M-2009.
- E) IT IS RECOMMENDED TO HAVE NO TRACES OR VIAS WITHIN THE KEEP OUT AREA.
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